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Application ID: 10669820
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First Named Inventor: Chung Tzu
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Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention	REINFORCED DIE PAD SUPPORT STRUCTURE	
Application Number:	10/669820 	
Date:	2003-09-24	
First Named Applicant:	Chung Hsing Tzu	
Confirmation Number:	5197	
Attorney Docket Number:	AMKOR090A	
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Submitted by:	Elec. Sign.	Sign. Capacity
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney
Documents being submitted us-ids	Files	ids3-usidst.xml us-ids.dtd us-ids.xsl
Comments		

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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	REINFORCED DIE PAD SUPPORT STRUCTURE						
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First Named Applicant:	Chung Tzu						
Attorney Docket Number:	AMKOR090A						
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Search string:	(5640047 or 5641997 or 5643433 or 5644169 or 5646831 or 5650663 or 5661088 or 5665996 or 5673479 or 5683806 or 5689135 or 5696666 or 5701034 or 5703407 or 5710064 or 5723899 or 5724233 or 5736432 or 5745984 or 5753532 or 5753977 or 5766972 or 5770888 or 5776798 or 5783861 or 5801440 or 5814877 or 5814881 or 5814883 or 5814884 or 5817540 or 5818105 or 5821457 or 5821615 or 5834830 or 5835988 or 5844306 or 5856911 or 5859471 or 5866939 or 5871782 or 5874784 or 5877043 or 5886397 or 5886398 or 5894108 or 5897339 or 5900676 or 5903049 or 5903050).pn.						
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
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Signature

Examiner Name	Date